CMOS LSI



No.1802C

SINGLE-CHIP 4-BIT MICROCOMPUTER (LOW-THRESHOLD INPUT, ON-CHIP FLT DRIVER)

The LC6514B is a microcomputer with FLT drivers. It is identical with the LC6510C in the internal architecture and instruction set. Since the normal/low-threshold level of input port A can be selected by option and the on-chip pull-down resistor can be bitwise connected to the FLT driver by option, the number of external parts used in the user equipment can be minimized, reducing the cost considerably.

(Note) The LC6514B heretofore in use has been improved by changing the value of the pull-down resistor to be contained in FLT drivers as shown below. When using the LC6514B, fully check that the new resistor value meets your application specifications.

, , ,		New resistor value Old resistor value						
		min	typ	max	min	typ	max	
"L"-level output current	lo _L	0.190	0.362	0.760	0.108	0.304	0.543	mΑ
(Output pull-down resistance)	(R _{PD})	(200)	(105)	(50)	(350)	(125)	(70)	$(k\Omega)$

Features

Low power dissipation

ROM capacity: 4096 x 8 bits RAM capacity: 256 x 4 bits

Subroutine stack: 8 levels (common with interrupt)

· On-chip OSC circuit

CR OSC:

800kHz typ.

Ceramic OSC: 400kHz, 800kHz, 1000kHz

External input: 1290kHz max. Power-down by 2 standby modes

HALT mode: Power dissipation saving by program standby during normal operation

HOLD mode: Power supply backup during power failure

Input/output ports

Input:

4 bits x 1 port

3 bits x 1 port

Input/output: 4 bits x 2 ports

Output:

4 bits x 4 ports

2 bits x 1 port

Interrupt

External interrupt:

Internal timer interrupt: 1

- · On-chip 4-bit prescaler and 8-bit program timer
- Instruction cycle time: 3.1µs (at 1290kHz)

Supply voltage

Normal operation: 4.0 to 6.0V

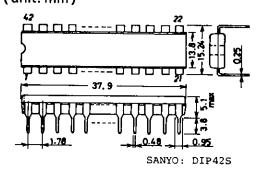
Memory hold:

1.8 to 6.0V

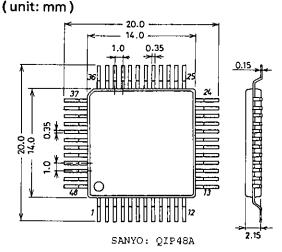
Instruction set common to the LC6502, LC6505 (BANK instruction added)

Package: DIP42S (shrink)
 QIP48

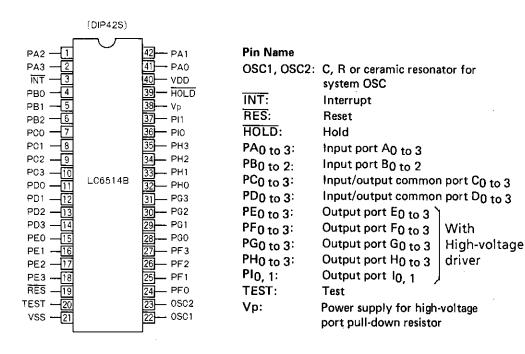
Package Dimensions 3025B-D42SIC (unit: mm)



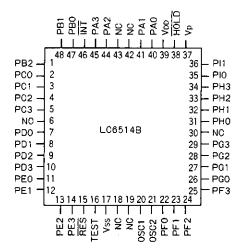
Package Dimensions 3052A-Q48AIC



Pin Assignment



[QIP48]



When mounting the QIP package version on the board, do not dip it in solder.

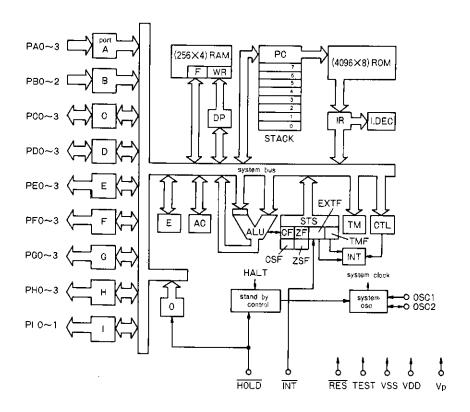
NC pin: No connection

LC6514B

Pin Description

Pin Name	Input/ Output	Function
INT	Input	Interrupt request input pin.
HOLD	Input	HOLD mode request input pin (Differs from the LC6502/05 in function.) Capable of being used as a general-purpose single-bit input port unless the standby mode is used.
RES	Input	Reset input pin.
PA _{0 to} 3	Input	Input port A ₀ to A ₃ (Normal voltage). Capable of 4-bit input and single-bit decision for branch. Used also for HALT mode release request input. Low threshold input for 4 bits selectable by option.
PB _{0 to 2}	Input	Input port B _{0 to} B ₂ (Normal voltage) Capable of 3-bit input and single-bit decision for branch.
PC _{0 to 3}	Input/ output	Input/output common port C ₀ to C ₃ (Normal voltage). Capable of 4-bit input and single-bit decision for branch during input. Capable of 4-bit output and single-bit set/reset during output.
PD _{0 to} 3	Input/ output	Input/output common port D ₀ to D ₃ (Normal voltage). Capable of 4-bit input and single-bit decision for branch during input. Capable of 4-bit output and single-bit set/reset during output.
PE _{0 to} 3	Output	Output port E ₀ to E ₃ (with high-voltage segment driver). Capable of 4-bit output and single-bit set/reset. Capable of 4-bit input of output latch contents and single-bit decision of output latch for branch. Use/nonuse of pull-down resistor bitwise selectable by option.
PF _{0 to} 3	Output	Output port F ₀ to F ₃ (with high-voltage segment driver). Capable of 4-bit output and single-bit set/reset. Capable of 4-bit input of output latch contents and single-bit decision of output latch for branch. Use/nonuse of pull-down resistor bitwise selectable by option.
PG _{0 to} 3	Output	Output port G ₀ to G ₃ (with high-voltage digit driver). Capable of 4-bit output and single-bit set/reset. Capable of 4-bit input of output latch contents and single-bit decision of output latch for branch. Use/nonuse of pull-down resistor bitwise selectable by option.
PH _{0 to} 3	Output	Output port H ₀ to H ₃ (with high-voltage digit driver). Capable of 4-bit output and single-bit set/reset. Capable of 4-bit input of output latch contents and single-bit decision of output latch for branch. Use/nonuse of pull-down resistor bitwise selectable by option.
Pl0, 1	Output	Output port Io, Io (with high-voltage digit driver). Capable of 2-bit output and single-bit set/reset. Capable of 2-bit input of output latch contents and single-bit decision of output latch for branch. Use/nonuse of pull-down resistor bitwise selectable by option.
OSC1	Input	Pin for supplying external clock. If the internal clock mode is used, C, R or a ceramic resonator is connected to this pin and pin OSC2.
OSC2	Output	Pin for externally connecting a resonance circuit for the internal clock mode.
√ _{DD}	Input	Power supply pin. Normally connected to +5V.
√ss	-	Connected to 0V power supply.
/P	Input	Power supply for high-voltage port pull-down resistor.
rest	Input	LSI test pin. Normally connected to Vss (0V).

System Block Diagram



RAM: Data memory ROM: Pro	ogram memory
F: Flag PC: Pro	ogram counter
WR: Working register INT: Int	terrupt control
AC: Accumulator IR: Ins	truction register
ALU: Arithmetic and logic unit I.DEC: Ins	truction decoder
DP: Data pointer CF, CSF: Car	rry flag
E: E register Car	rry save flag
CTL: Control register ZF, ZSF: Zei	ro flag
OSC: Oscillator Zer	ro save flag
TM: Timer EXTF: Ex	ternal interrupt request flag
STS: Status register TMF: Int	ernal interrupt request flag

Absolute Maximum Ratings at Ta=25 $^{\circ}$ C, VSS=0V (VDD=5V \pm 20% unless otherwise specified)

				unit
Maximum Supply Voltage	Voo max		$-0.3 \sim +7.0$	V
Input Voltage	VIN (1)	Inputs other than Vp	$-0.3 \sim V_{DD} + 0.3$	√ (Note 1)
	VIN (2)	Vp	VDD-45~VDD+0.3	V
Output Voltage	Vout (1)	Outputs other than ports E, F, G, H, I	$-0.3 \sim VDD + 0.3$	V
	Vout (2)	Ports E, F, G, H, I	VDD-45~VDD+0.3	V
Peak Output Current	lo (1)	Each pin of ports C, D	$-2.0 \sim +2.0$	mA
	lo (2)	Each pin of ports E, F	-10~0	mΑ
	lO (3)	Each pin of ports G, H, I	−15 ~ 0	mA
	lo (4)	All pins of ports C to I	-90∼+16	mΑ
Allowable Power	Pd max (†)	DIP package, Ta=-30 to +70°C	600	mW
Dissipation	Pd max (2)	Flat package, Ta= -30 to $+70^{\circ}$ C	400	mW
Operating Temperature	Торг		$-30 \sim +70$	\mathcal{C}
Storage Temperature	Tstg		− 55∼+125	$^{\circ}$

Note 1: For pin OSC1, up to oscillation amplitude generated when internally oscillated under the recommended oscillation conditions in Fig. 3 is allowable.

Recommended Operating Conditions at Ta=-30 to $+70^{\circ}$ C, V_{SS}=0V (V_{DD}=4.0 to 6.0V unless otherwise specified)

			min	typ	max	unit
Operating Supply Voltage	VDD		4.0	5.0	6.0	V
Power-down Supply Voltage	VDD(MR)	HOLD=V _{IL(4)} , HOLD mode	1.8		6.0	V
"H"-Level Input Voltage	VIH (1)	Ports A to D, port A: "normal threshold	0.7Vc	DD	VDD	V
		input"				
	VIH 27	VDD=4.5 to 5.5V, port A: "low threshold	1.9		VDD	V
		input"				
W. W. A	VIH 3:	INT, RES, HOLD, OSC1 pins	0.8V0		VDD	V
"L"-Level Input Voltage	VIL (1)	Ports A to D, port A: "normal threshold input"	Vss	0.3	3VDD	V
	VIL '2)	V _{DD} =4.5 to 5.5V, port A: "low threshold input"	Vss		0.5	V
	VIL (3)	INT, RES, OSC1 pins	Vss	0.2	2Vdd	V
	VIL (4)	V _{DD} =1.8 to 6.0V, HOLD , TEST pins	Vss	0.7	2Vdd	V
Operating Clock Frequency	fextosc	At external clock input, See Fig. 1.	222		1290	kHz
"H"-Level Clock Pulse	tw¢H	4	0.3			μ5
Width						
"L"-Level Clock Pulse	twøL	//	0.3			μS
Width						
Clock Input Rise	toscR	4			0.2	μS
Time						
Clock Input Fall	toscF	//			0.2	μS
Time						
External Capacitance for CR OS	C Cext	See Fig. 8		220±5	%	ρF
External Resistance for CR OSC	Rext	See Fig. 6		6.8 ± 1	%	kΩ
External Circuit Constants	R1, R2	See Fig. 3				
for Ceramic OSC	C1, C2					
Standby Timing	t _{VDDR}	See Fig. 6, V _{DD} =1.8 to 6.0V	0			μS
	tvoor	4	0			μS
Allowable Delay in	t _{DL}	See Figs. 9, 10.		(N-3)	·Tc	μS
Key Scan Circuit	toH	4		(N-3)	· Tc	μS

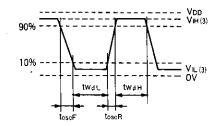
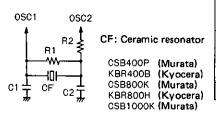




Fig. 2 Recommended Oscillator for CR OSC

Fig. 1 OSC1 Pin Input Waveform



Center Frequency	CF	C1(pF)	C2(pF)	R1(kΩ)	R2(kΩ)
400kHz	CSB400P (Murata)	470	470	1000	1.5
40000	KBR400B(Kyocera)	470	470	1000	1.5
	CSB800K (Murata)	220	220	1000	1.0
800kHz	KBR800H(Kyocera)	220	220	1000	1.0
	RDROOOH(Rydcera)	150	150	1000	1.5
1000kHz	CSB1000K (Murata)	100	100	1000	1.5

C1, C2: Tolerance ±10%

Fig. 3 Recommended Oscillator for Ceramic OSC

R1, R2: Tolerance ±5%

"H"-Level Input Current In All input pins except Vp, VIN=VSS 1	Electrical Characteristics/Ta=	=–30 to +70°C	, V _{DD} =5V ±20%, V _{SS} =0V	min	typ	max	unit
"H"-Level Output Voltage VOH(1) Ports C, D: IQH=-1mA VDD-2.0 V VOH(2) Ports C, D: IQH=-100µA VOD-0.5 V VOH(3) Ports E, F: IQH=-2mA VDD-1.0 V VOH(4) Ports E, F: IQH=-1mA VDD-1.0 V VOH(4) Ports G, H, I: IQH=-1mA VDD-1.8 V VOH(5) Ports G, H, I: IQH=-1mA VDD-1.0 V VOH(7) Ports G, H, I: IQH=-1mA VDD-0.5 V "L"-Level Output Voltage VOL(1) Ports G, H, I: IQH=-1mA VDD-0.5 V "L"-Level Output Current VOL(2) Ports G, H, I: VP=-35V, output Tr OFF, output Open, with pull-down resistor -33 V "L"-Level Output Current IQL Ports E, F, G, H, I: VP=-35V, output Tr OFF, output Open, with pull-down resistor -33 V "L"-Level Output Current IQL Ports E, F, G, H, I: VP=-35V, output Tr OFF, output Open, with pull-down resistor -30 (EQD) (EQ	"H"-Level Input Current	IIН	All input pins except Vp, VIN=VDD			1	μΑ
VOH(2)		lıı_	All input pins except Vp, VIN=VSS	- 1			μΑ
VOH(3)	"H"-Level Output Voltage	V0H(1)	Ports C, D: I _{OH} =-1mA	DD-2.0			V
VoH(4)		VOH(2)	Ports C, D: $I_{OH}=-100\mu$ A	0.5			V
All ports I OH=-1mA		VOH(3)	Ports E, F: I _{OH} =–2mA	oo—1.0			V
VOH(5) Ports G, H, I: I _O H=-10mA VOD-1.8 VOH(5) VOH(6) Ports G, H, I: I _O H=-2mA VOD-1.0 VOH(7) Ports G, H, I: I _O H=-1mA VOD-1.5 VOH(7) Ports G, H, I: I _O H=-1mA VOD-0.5 VOH(7) Ports G, H, I: I _O H=-1mA VOD-0.5 VOH(7) Ports G, H, I: I _O H=-1mA VOD-0.5 VOH(7) Ports G, H, I: I _O H=-1mA VOD-0.5 VOH(7) Ports G, H, I: V _O H=-35V, output Tr OFF, output OFF, G, H, I: V _O H=-35V, output Tr OFF, output OFF, G, H, I: V _O H=-35V, output Tr OFF, output OFF, G, H, I: V _O H=-35V, output Tr OFF, output OFF, G, H, I: V _O H=-35V, output OFF, G, H, I: V _O		VOH(4)	Ports E, F: I _{OH} =-1mA, V _I	DD-0.5			V
VOH(6) Ports G, H, I: IOH=-2mA VOD-1.0 VOH(7) Ports G, H, I: IOH=-1mA, VOD-0.5 VOH(7) Ports G, H, I: IOH=-1mA, VOD-0.5 VOH(7) Ports G, H, I: IOH=-1mA, VOD-0.5 VOH(7) Ports G, H, I: IOH=-1mA VOD-0.5 VOH(7) Ports G, H, I: VP=-35V, output Tr OFF, -33 VOD-10.1 VOL(2) Ports E, F, G, H, I: VP=-35V, output Tr OFF, -33 VOD-10.1 VOL(2) Ports E, F, G, H, I: VP=-35V, VOL(20) (105) (50) (kΩ) VOL(20) VOL(20) VOL(20) VOL(20) VOL(20) (105) (50) (kΩ) VOL(20) VOL(20) VOL(20) VOL(20) (105) (50) (kΩ) VOL(20) VOL(20) VOL(20) (105) (50) (kΩ) VOL(20) VOL(20) VOL(20) (105) (50) (kΩ) VOL(20) VOL(20) (105) (50) (kΩ) VOL(20) VOL(20) (105)			all ports IOH=-1mA	•			
VoH(7)		VOH(5)	Ports G, H, I: IOH=-10mA	on—1.8			V
All ports I OH=-1mA O.4 VOL(1) Ports C, D: I OH=1mA O.4 VOL(2) Ports E, F, G, H, I: Vp=-35V, output Tr OFF, output open, with pull-down resistor IOL (RPD) Ports E, F, G, H, I: Vp=-35V, output Tr OFF, output open, with pull-down resistor IOL (RPD) Ports E, F, G, H, I: Vp=-35V, O.190 O.362 O.760 mA (Output Pull-down resistor) VOL=3V, VDD=5V, (200) (105) (50) (kΩ)		VOH(6)	Ports G, H, I: IOH=-2mA	DD-1.0			V
"L"-Level Output Voltage VOL(1) Ports C, D: I _{OL} =1mA 0.4 V VOL(2) Ports E, F, G, H, I: Vp=-35V, output Tr OFF, output OFF -33 V "L"-Level Output Current (Output Pull-down resistor) IOL (RPD) Ports E, F, G, H, I: Vp=-35V, output Tr OFF, volupid Pull-down resistor 0.190 0.362 0.760 mA Output OFF Leak Current IOFF(1) Ports E, F, G, H, I: Vp=-35V, output Tr OFF, volupid Pull-down resistor (200) (105) (50) (kΩ) Output OFF Leak Current IOFF(1) Ports C, D: VOUT=VDD 1.0 μA IOFF(2) Ports C, D: VOUT=VDD -1.0 μA IOFF(3) Port E to I: VOUT=VDD, OD output Pull-down Policy Poli		Voh(7)	Ports G, H, I: I _{OH} =-1mA,	DD-0.5		•	V
VOL(2) Ports E, F, G, H, I: Vp=-35V, output Tr OFF, output Current output open, with pull-down resistor OLD Ports E, F, G, H, I: Vp=-35V, O.190 O.362 O.760 mA			ail ports IOH=-1mA				
output open, with pull-down resistor $(DL (RPD))$ $CL (RPD)$ $CL $	"L"-Level Output Voltage		Ports C, D: IOL=1mA			0.4	V
"L"-Level Output Current (Output Pull-down resistor) IQL (RPD) Ports E, F, G, H, I: Vp=-35V, VD=5V, VD=5V, VDD=5V, With pull-down resistor 0.190 (3.62 0.760 mA) mA Output OFF Leak Current IOFF(1) Ports C, D: VOUT=VDD 1.0 μA 1.0 μA μA IOFF(2) Ports C, D: VOUT=VSS -1.0 μA 30 μA μA IOFF(3) Port E to I: VOUT=VDD, OD output IOFF(4) Port E to I: VOUT=VDD-40V, OD output IOFF(4) Port E to I: VOUT=VDD IOFF(4) Port E to I: VOUT=VDD-40V, OD output IOFF(4) Port E to I: VOUT=		V _{OL(2)}	Ports E, F, G, H, I: Vp=-35V, output Tr O	FF,	1	-33	٧
Coutput Pull-down resistor CRPD VOL=3V, VDD=5V, with pull-down resistor VOUT=VDD 1.0 μA			· · · · · · · · · · · · · · · · · · ·		F		
with pull-down resistor Output OFF Leak Current IOFF(1) Ports C, D: VOUT=VDD 1.0 μA IOFF(2) Ports C, D: VOUT=VSS -1.0 μA IOFF(3) Port E to I: VOUT=VDD, OD output 30 μA IOFF(4) Port E to I: VOUT=VDD-40V, OD output -30 μA Clock OSC Frequency fCFOSC(1) Recommended conditions for ceramic OSC, 384 400 416 kHz for Ceramic OSC at OSC circuit in Fig. 3 (Note 1) fCFOSC(2) " 768 800 832 kHz 600 1000 1040 kHz fCFOSC(3) " 960 1000 1040 kHz 100 kHz for CR OSC Cext=220pF, Rext=6.8kΩ, 600 800 1220 kHz for CR OSC at OSC circuit in Fig. 2 Current Dissipation IDD(1) At CR OSC, Cext=220pF, Rext=6.8kΩ, 01.0 2.0 mA IDD(2) At ceramic OSC (800kHz), output pin open, input pin, VIN=VDD IDD(2) At ceramic OSC (800kHz), output pin open, input pin, VIN=VDD IDD(3) HALT mode, VDD=4.0 to 6.0V, 10 μA IDD(4) HALT mode, VDD=1.8 to 6.0 V, 10 μA IDD(4) HOLD mode, VDD=1.8 to 6.0 V, 10 μA At test circuit in Fig. 5					0.362		mA
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		(HPD)	_ ··	(200)	(105)	(50)	(kΩ)
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	Output OFF Leak Current	IOFF(1)	Ports C, D: VOUT=VDD			1.0	μΑ
$\begin{tabular}{ l l l l l l l l l l l l l l l l l l l$		IOFF(2)	Ports C, D: VOUT=VSS	-1.0			μА
Clock OSC Frequency fcFoSc(1) Recommended conditions for ceramic OSC, 384 400 416 kHz at OSC circuit in Fig. 3 (Note 1) fcFoSc(2) " 768 800 832 kHz fcFoSc(3) " 960 1000 1040 kHz fcFoSc(3) k	·	IOFF(3)				30	μA
Clock OSC Frequency fcFoSC(1) Recommended conditions for ceramic OSC, 384 400 416 kHz for Ceramic OSC at OSC circuit in Fig. 3 (Note 1)		IOFF(4)	·	-30			μΑ
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Clock OSC Frequency	fcFosc(1)		384	400	416	kHz
Clock OSC Frequency fCROSC Cext=220pF, Rext=6.8k Ω , 600 800 1220 kHz for CR OSC at OSC circuit in Fig. 2 Current Dissipation IDD(1) At CR OSC, Cext=220pF, Rext=6.8k Ω , output pin open, input pin, VIN=VDD IDD(2) At ceramic OSC (800kHz), output pin open, input pin, VIN=VDD IDD(3) HALT mode, VDD=4.0 to 6.0V, at test circuit in Fig. 4 IDD(4) HOLD mode, VDD=1.8 to 6.0 V, at test circuit in Fig. 5	for Ceramic OSC		at OSC circuit in Fig. 3 (Note 1)				
Clock OSC Frequency fCROSC Cext=220pF, Rext=6.8k Ω , 600 800 1220 kHz for CR OSC at OSC circuit in Fig. 2 Current Dissipation IDD(1) At CR OSC, Cext=220pF, Rext=6.8k Ω , output pin open, input pin, VIN=VDD IDD(2) At ceramic OSC (800kHz), output pin open, input pin, VIN=VDD IDD(3) HALT mode, VDD=4.0 to 6.0V, at test circuit in Fig. 4 IDD(4) HOLD mode, VDD=1.8 to 6.0 V, at test circuit in Fig. 5		fcFosc(2)	"	768	800	832	kHz
for CR OSC at OSC circuit in Fig. 2 Current Dissipation IDD(1) At CR OSC, Cext=220pF, Rext=6.8k Ω , 1.0 2.0 mA output pin open, input pin, VIN=VDD IDD(2) At ceramic OSC (800kHz), output pin open, 1.0 2.0 mA input pin, VIN=VDD IDD(3) HALT mode, VDD=4.0 to 6.0V, 10 μ A at test circuit in Fig. 4 IDD(4) HOLD mode, VDD=1.8 to 6.0 V, 10 μ A at test circuit in Fig. 5		fCFOSC(3)	"	960	1000	1040	kHz
Current Dissipation IDD(1) At CR OSC, Cext=220pF, Rext=6.8k Ω , 1.0 2.0 mA output pin open, input pin, VIN=VDD IDD(2) At ceramic OSC (800kHz), output pin open, 1.0 2.0 mA input pin, VIN=VDD IDD(3) HALT mode, VDD=4.0 to 6.0V, at test circuit in Fig. 4 IDD(4) HOLD mode, VDD=1.8 to 6.0 V, at test circuit in Fig. 5	Clock OSC Frequency	fcrosc	Cext=220pF, Rext=6.8k Ω ,	600	800	1220	kHz
output pin open, input pin, V _{IN} =V _{DD} DD(2) At ceramic OSC (800kHz), output pin open, 1.0 2.0 mA input pin, V _{IN} =V _{DD} DD(3) HALT mode, V _{DD} =4.0 to 6.0V, 10 μA at test circuit in Fig. 4 DD(4) HOLD mode, V _{DD} =1.8 to 6.0 V, 10 μA at test circuit in Fig. 5	for CR OSC		at OSC circuit in Fig. 2				
output pin open, input pin, $V_{IN}=V_{DD}$ At ceramic OSC (800kHz), output pin open, 1.0 2.0 mA input pin, $V_{IN}=V_{DD}$ BDD(3) HALT mode, $V_{DD}=4.0$ to 6.0V, 10 μ A at test circuit in Fig. 4 BDD(4) HOLD mode, $V_{DD}=1.8$ to 6.0 V, 10 μ A at test circuit in Fig. 5	Current Dissipation	IDD(1)	At CR OSC, Cext=220pF, Rext=6.8kΩ,		1.0	2.0	mΑ
IDD(2)							
input pin, $V_{\text{IN}} = V_{\text{DD}}$ HALT mode, $V_{\text{DD}} = 4.0$ to 6.0V, at test circuit in Fig. 4 HOLD mode, $V_{\text{DD}} = 1.8$ to 6.0 V, at test circuit in Fig. 5		IDD(3)	*** ==		1.0	2.0	mΑ
HALT mode, V_{DD} =4.0 to 6.0V, 10 μ A at test circuit in Fig. 4 HOLD mode, V_{DD} =1.8 to 6.0 V, 10 μ A at test circuit in Fig. 5				•			
at test circuit in Fig. 4 IDD(4) HOLD mode, VDD=1.8 to 6.0 V, 10 μ A at test circuit in Fig. 5		IDD(3)				10	μА
HOLD mode, V_{DD} =1.8 to 6.0 V, 10 μ A at test circuit in Fig. 5						•	-
at test circuit in Fig. 5		IDD(4)	•			10	μΑ
101 40 f 00 W - 11 f						, -	,
	(Note 1) fCFOS	C: Oscillatable		Conti	nued o	n next i	nane

Continued from preceding	g page.		min	typ	max	unit
Input Capacitance	CIN	f=1MHz		5		pF
Output Capacitance	Cour	f=1MHz, output: high impedance		10		рF
Input/Output Capacitance	Cio	<i>n</i>		10		рF

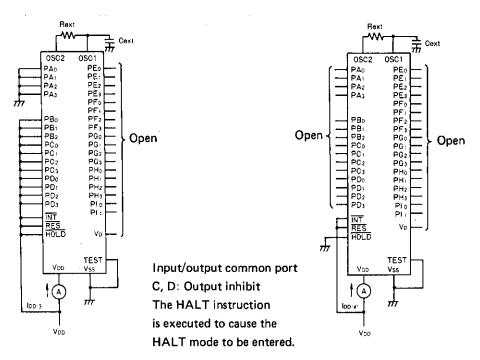


Fig. 4 IDD(3) Test Circuit

Fig. 5 IDD(4) Test Circuit

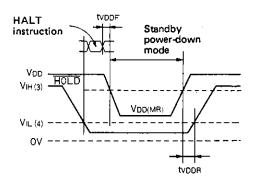
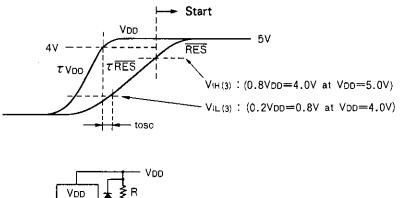
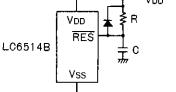


Fig. 6 Standby Mode Timing

(Note)
During the HALT instruction execution cycle, no chattering must be applied to the HOLD pin and PAO to 3 pins.





T VDD: Power supply rise time constant

 $au_{\overline{
m RES}}$: $\overline{
m RES}$ pin rise time constant

Fix C, R so that $\tau V_{DD} \le \tau \overline{RES}$, $t_{OSC} \ge 10$ msec is

yielded. (tOSC: OSC stabilized time)

Fig. 7 Initial Reset Timing

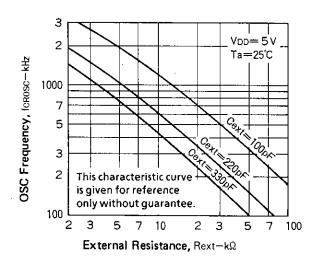
CR OSC characteristic of LC6514B

Fig. 8 shows the CR OSC characteristic of the LC6514B. For the variation range of CR OSC frequency of the LC6514B, the following is guaranteed at external constants of Cext=220pF, Rext=6.8kohm only. The outgoing inspection is performed under this condition only.

600kHz
$$\leq$$
 fcrosc \leq 1220kHz $\left(\begin{array}{c} Ta = -30\% \sim +70\% \\ VDD = 4 \sim 6 \end{array}\right)$

If any other constants than specified above are used, the range of Rext=5k to 50kohm, Cext=100p to 300pF must be observed. (See Fig. 8.)

Fig. 8 fCROSC. - Rext



- Note 1. The OSC frequency at V_{DD}=5V, Ta=25°C must be 800kHz or less.
- Note 2. The OSC frequency at $V_{DD}=4$ to 6V, Ta= -30 to $+70^{\circ}$ C must be within the operation clock frequency range (222kHz to 1290 kHz).

Proper cares in using the IC

[Digit drive signal-used key scan]

When key-scanning with the FLT digit drive signal in Fig. 9 and inputting the return signal to port A, the following must be observed.

- (a) Estimate voltage drop (VoN) in the output transistor using the current flowing in an FLT used and the V-I characteristic of the output port of the LC6514B.
- (b) Estimate voltage drop (VSW) in the switch circuit.
- (c) Check to see that (VON + VSW) meets the VIH/VIL requirement of the input port.

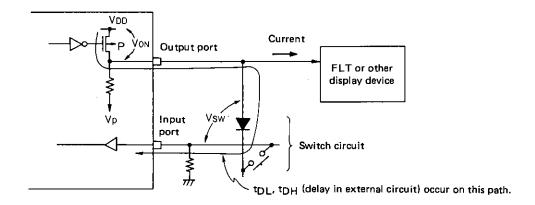
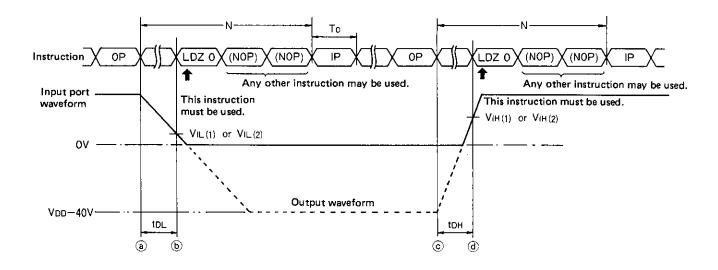


Fig. 9 Sample Key Scan Application

For the key scan application in Fig. 9, make the program considering the delay in the external circuit and the input delay shown below.



N: Number of instruction cycles existing between instruction (OP, SPB, RPB) used to output data to output port and instruction (IP, BP, BNP) used to input data from input port. (Number of instruction cycles to be programmed according to the length of tpl, tpH) tpl, tpH: Delay in external circuit from output port to input port.

When the IP instruction is used to input the return signal as shown in Fig. 10, the input delay must be considered and three instructions are placed between the IP instruction and the crossing of input port waveform and $V_{IL(1)}$ or $V_{IL(2)}$, $V_{IH(1)}$ or $V_{IH(2)}$ respectively.

Some instructions must be placed additionally according to the length of delay (tpl, tph) in the external circuit after the digit drive signal is delivered with the execution of the OP instruction (a) and c).

<Notes for Standby Function Application>

[Proper cares in using standby function]

The LC6514B provides the standby function called HALT, HOLD mode to minimize the current dissipation when the program is in the wait state. The standby function is controlled by the HALT instruction, the HOLD pin, RES pin. A peripheral circuit and program must be so designed as to provide precise control of the standby function. In most applications where the standby function is performed, voltage regulation, instantaneous break of power, and external noise are not negligible. When designing an application circuit and program, whether or not to take some measures must be considered according to the extent to which these factors are allowed.

This section mainly describes power failure backup for which the standby function is mostly used. A sample application circuit where the standby function is performed precisely is shown below and notes for circuit design and program design are also given below. When using the standby function, the application circuit shown below must be used and the notes must be also fully observed. If any other method than shown in this section is applied, it is necessary to fully check the environmental conditions such as power failure and the actual operation of an application equipment.

[Sample application and notes]

When using the HOLD mode, an application circuit and program must be designed with the following in mind.

- (1) The supply voltage at the standby state must not be less than specified.
- (2) Input timing of each control signal (HOLD, RES, port A, INT, etc.) at the standby initiate/release state.
- (3) Release operation must not be overlapped at the time of execution of the HALT instruction.

A sample application where the standby function is used for power failure backup is shown below as a concrete method to observe these notes. A sample application circuit, its operation, and notes for program design are given below.

- Sample application where the standby function is used for power failure backup
 Power failure backup is an application where power failure of the main power source is detected by the HOLD pin,
 etc. to cause the HOLD mode to be entered so that the current dissipation is minimized and a backup capacitor
 is used to retain the contents of the internal registers even during power failure.
- 1-1. Sample application circuit (CF OSC)

Fig. 11 shows a CF OSC-applied circit where the standby function is used for power failure backup.

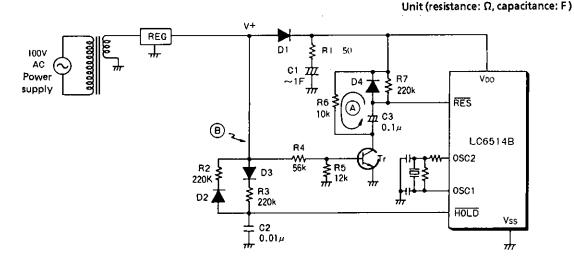
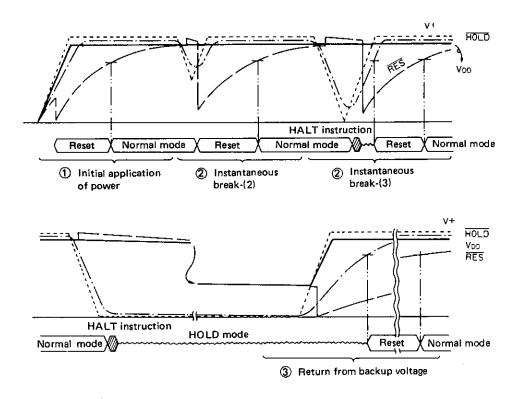


Fig. 11 Sample Application Circuit

1-2. Operating waveform

The operating waveform in the sample application circuit in Fig. 11 is shown below. The mode is roughly divided as follows:

- 1) Initial application of power
- (2) Instantaneous break
- 3 Return from backup mode



- 1-3. Operation of sample application circuit
- (1) At the time of initial application of power

A reset occurs and the execution of the program starts at address 000H of the program counter (PC).

- 2 At the time of instantaneous break
 - (1) At the time of very short instantaneous break
 - The execution of the program continues.
 - (2) At the time of instantaneous break being a little longer than (1)

(When the RES input voltage meets VIL and HOLD input voltage does not meet VIL)

A reset occurs during the execution of the program and the execution of the program starts at address 000H of the program counter (PC).

Since the HOLD request signal is not applied to the HOLD pin, the HOLD mode is not entered.

(3) At the time of long instantaneous break (When both of the RES input voltage and HOLD input voltage meet VII)

The HOLD request signal is applied to the HOLD pin and the HOLD mode is entered.

When V+ rises after instantaneous break, a reset occurs to release the HOLD mode and the execution of the program starts at address 000H of the program counter (PC).

3 At the time of return from backup voltage

A reset occurs and the execution of the program starts at address 000H of the program counter (PC).

1-4. Notes for circuit design

① How to fix C3, R6, C2, R2

Fix closed loop (A) discharge time constants C3, R6 and \overline{HOLD} pin charge time constants C2, R2 so that closed loop (A) fully discharges before the \overline{HOLD} input voltage gets lower than $V_{|L|}$ at the time of instantaneous break and the \overline{RES} input voltage is sure to get lower than $V_{|L|}$ (a reset occurs) when V+ rises after instantaneous break where the \overline{HOLD} input voltage gets lower than $V_{|L|}$.

(2) How to fix C3, R7

Fix $\overline{\text{RES}}$ pin charge time constants C3, R7 so that when power is applied initially or the HOLD mode is released the CF OSC oscillates normally and the $\overline{\text{RES}}$ input voltage exceeds V_{IH} and the program starts running.

3 How to fix R4, R5

Fix Tr bias constants R4, R5 so that when V+ rises after instantaneous break the RES input voltage gets lower than V_{IL} (brought to "L" level) before the HOLD input voltage exceeds V_{IH} (brought to "H" level).

4 How to fix C2, R3

Fix \overline{HOLD} pin charge time constants C2, R3 so that when the HOLD mode is released from the backup mode the \overline{HOLD} input voltage does not exceed V_{IH} (not brought to "H" level) until the \overline{RES} input voltage gets lower than V_{IL} (brought to "L" level).

Fix C3, R7 and C2, R3 so that the time interval from the moment the HOLD input voltage exceeds VIH until the RES input voltage exceeds VIH is longer than the CF OSC stabilizing time.

(5) When the load is heavy or the polling interval is long

Since C1 discharges largely, increase the capacity of C1 or separate (B) detection from V+ and use a power supply or signal that rises faster than V+.

1-5. Notes for software design

When the HOLD request signal is detected, the HALT instruction is executed immediately. A concrete example is shown below.

- 1 An interrupt is inhibited before polling the HOLD request pin (HOLD pin).
- Polling of the HOLD pin and the HALT instruction are programmed consecutively.

[Concrete example]

RCTL 3 ; EXTEN, TMEN + 0 (External, timer interrupt inhibit)

BPO AAA ; Polling of the HOLD pin (If "H" level, a branch occurs to AAA.)

HALT ; The HOLD mode is entered.

Application development tools

Evaluation chip (LC6597), simulation chip (LC65PG97) and the dedicated equipment called "application development tools" are available to facilitate application development of the LC6514B.

SDS-410 system

This is a combination of floppy disk-provided CPU, CRT, and printer. This system enables application development programs of microcomputers to be prepared (edited, assembled) very speedily and efficiently in assembly language. By connecting the EVA-410 to the CPU, programs can be debugged and assembled data can be written into the EPROM (using EPROM WRITER function contained in the EVA-410).

EVA-410

This is an evaluation kit having EPROM WRITER function, function of parallel/serial data communication with external equipment (SDS-410, etc.). This kit enables application development programs to be corrected or debugged on the machine language level.

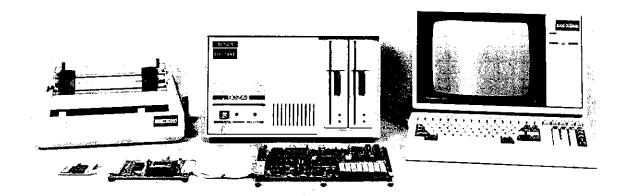
● EVA-TB3B

This is a board which is connected with the EVA-410 to develop programs dedicated to the LC6514B.

EVA-97-14B

Simulation chip (LC65PG97) is identical with the LC6510C in the I/O port breakdown voltage and pin assignment. Since the LC6514B has high-voltage output ports and differs partially in the pin assignment, conversion board "EVA-97-14B" with high-voltage drivers is used to evaluate the LC6514B.

(Note) The threshold level of input port A of the LC6514B can be selected to be normal/low level by option. However, since port A of the EVA-TB3B, EVA-97-14B is of normal threshold input type, they cannot be used to evaluate the low threshold input version of the LC6514B.



LC6514B

APPENDIX LC6510 Series Instruction Set (by Function)

M: Memory
M(DP): Memory addressed by DP
P(DPL): Input/output port addressed by DPL
PC: Program counter
STACK: Stack register (), []: Contents Symbols Meaning Transfer and direction AC: ACt: Accumulator Addition Accumulator bit t CF: CTL: Subtraction Carry flag AND Control register OR DP: Data pointer TM: Timer Exclusive OR Timer (internal) interrupt request flag E: E register TMF:

EXTF: External interrupt request flag At, Ha, La: Working register

Fn: Flag bit n ZF: Zero flag

_	ГII.	riag bit fi				_	ero riay				
tion	Ction		Instruction code		X.	E	s		Sta	tus	
Instruction		Mnemonic	D7D6D5D4	D3O2D1D0	By te	1 73	Function	Description	fla after		Remarks
Ę	CLA	Clear AC	1100	0000	1	1	AC - 0 .	The AC contents are cleared.	ZF		* 1
instructions	CLÇ	Clear CF	1110	0001	1	1	CF ←0	The CF is reset.	Ī	CF	
instr	STC	Set CF	1 1 1 1	0001	1	1	CF ←1	The CF is set.		CF	
.5	CMA	Complement AC	1110	1011	1	1	AC ←(AC)	The AC contents are complemented (zero bits become 1, one bits become 0).	ZF		
manipulat	INC	Increment AC	0000	1 1 1 0	7	1	AC ←(AC) +1	The AC contents are incremented +1.	ZF	CF	
Į,	DEÇ	Decrement AC	0000	1 1 1 1	1	ī	AC ←(AC) -1	The AC contents are decremented -1,	ZF	ÇF	
Accumulator r	RAL	Rotate AC left through CF	0000	0001	1	1	AC0 ←(CF), ACn+1← (ACn), CF ←(AC3)	The AC contents are shifted left through the CF.	ZF	CF	
Ę	TAE	Transfer AC to E	0000	0011	1	1	E ←(AC)	The AC contents are transferred to the E.			
٤	XAE	Exchange AC with E	0000	1 1 0 1	1	1	(AC) ≒(E)	The AC contents and the E contents are exchanged.			
ē	INM	Increment M	0010	1110	1	1	$M(DP) \leftarrow (M(DP)) + 1$	The M(OP) contents are incremented +1.	Z۶	CF	
ù lat	DE M	Decrement M	0010	1 1 1 1	1	1	M(DP) - (M(DP)) -1	The M(DP) contents are decremented -1,	ZF	CF	• • •
Memory manipulation instructions	SMB bit	Set M data bit	0000	1 0 8 18 0	,	i	M(DP. B, B ₀) 1	A single bit of the M(DP) specified by B1B0 is set.			
Memor	RM8 bit	Reset M data bit	0010	1 O B 1 B o	,	1	M(DP, B₁8₀) ←0	A single bit of the M(DP) specified by B1B0 is set.	ZF		
	AD	Add M to AC	0110	0000	1	1	AC -(AC) + (M(DP))	The AC contents and the M(DP) contents are binery-added and the result is placed in the AC.	ZF	CF	
	ADC	Add M to AC with CF	0010	0000	1	1	AC ←(AC) + (M(DP)) +(CF)	The AC, CF, M(DP) contents are binary- added and the result is placed in the AC.	ZF	CF	
	DAA	Decimal adjust AC in addition	1110	0110	1	1	AC +(AC) + 6	6 is added to the AC contents.	ZF		148
	DAS	Decimal adjust AC in subtraction	1110	1010	1	1	AC ←(AC)+10	10 is added to the AC contents.	ZF		
Operation/comparison instructions	EXL	Exclusive or M to AC	1 1 1 1	0101	1	1	AC ←(AC) ¥ (M(DP))	The AC contents and the M(DP) contents are exelusive-ORed and the result is placed in the AC.	ZF		
ison inst	AND	And M to AC	1110	0 1 1 1	1	1	AC ←(AC) ∧ (M(DP))	The AC contents and the M(DP) contents are ANDed and the result is placed in the AC.	ZF		
сошра	OR	Or M to AC	1110	0101	1	1	AC -(AC)V (M(DP))	The AC contents and the M(DP) contents are ORed and the result is placed in the AC.	ZF		
tion/	СМ	Compare AC with M	1111	1011	1	1	(M(DP))+(AC)+1	The AC contents and the M(DP) contents are compared and the CF and ZF are set/	ZF	CF	
Opera								Comparison result	ļ		
	CI data	Compare AC with immediate data	0010	1 1 0 0 3 2 1 0	2	2	13121110 +(AC)+1	The AC contents and immediate data 13121110 are compared and the ZF and CF are set/reset.	ZF	CF	
								$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			
	CLI data	Compare DPL with immediate data	0 0 1 0 0 1 0 1	1 1 0 0 13121110	2	2	(DPL) ¥13121110	The DPL contents and immediate data 1312(110) are compared.	ZF		
	LI data	Load AC with immediate data	1100	13121,10	1	1	AC -13121110	Immediate data 13121110 is loaded in the AC.	2F		* 1
	S	Store AC to M	0 0 0 0	0010	1	1	M(DP) ←(AC)	The AC contents are stored in the M(DP),			
	L	Load AC from M	0010	0001	1	1	AC ← (M(DP))	The M(DP) contents are loaded in the AC.	ZF		
tions	XM data	Exchange AC with M. then modify DPH with immediate data	1010	O M ₂ M ₁ M ₀	1	2	(AC) \$ (M(DP)) DP _H ← (DP _H) ↓ 0 M ₂ M ₁ M ₀	The AC contents and the M(DP) contents are exchanged. Then, the DPH contents are modified with the contents of (DPH) VDM2M1M0.	ZF		The ZF is set/ reset according to the result of IDPHI-VOM2
Load/store instructions	x	Exchange AC with M	1010	0000	1	2	(AC) ≒ (M(DP))	The AC contents and the M(DP) contents are exchanged.	ZF		M1M0. The ZF is set/ reset according to the DPH contents at the time of instruc- tion execution.
Load/s	ΧI	Exchange AC with M. then increment DPL	1 1 1 1	1110	3	2	(AC) ≒ (M(DP)) DPL ←(DPL) +1	The AC contents and the M(DP) contents are exchanged. Then, the DPL contents are incremented +1.	ZF		The ZF is set/ reset according to the result of (DPL + 1).
1	XD	Exchange AC with M, then decrement DPL	1 1 1 1	1 1 1 1	1	2	(AC) \$ (M(DP)) DPL +(DPL)-1	The AC contents and the M(DP) contents are exchanged. Then, the DPL contents are decremented -1.	ŻF		The ZF is set/ reset according to the result of
	AT BL	Read table data from program ROM	0110	0011	1	2	AC.E←ROM (PCh.E.AC)	The contents of ROM addressed by the PC whose low-order 8 bits are replaced with the E and AC contents are loaded in the AC and E.			(OFE - 1).
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LC6514B

Instruction		Mnemonic			on code	Bytes	Cycles	Function	Description	Status flag	Remarks
octions Ins	LDZ data	Load DPH with Zero and DPL with immediate		_	D ₃ D ₂ D ₁ D ₀	1	1	DPH ←0 DP ω ←13 2 1 0	The DPH and OPL are loaded with 0 and immediate data 1312110 respectively.	affected	
instr	LHI data	data respectively	010	0 1	13 12 11 10	1	1	DPH ← 13121110	The DPH is loaded with immediate data		
lation		immediate data				_	_	-	(3)2(1)0.		
aludine	IND	Increment DPL	1 1 1	\rightarrow	1 1 1 0	1	1	DPL ← (DPL) + 1	The DPL contents are incremented +1,	ZF	
E	DED	Decrement DPL	1 1 1	<u> </u>	1 1 1 1	1	1	DP _L ← (DP _L) — 1	The DPL contents are decremented -1.	ZF	
pointer	TAL	Transfer AC to DPL	1 1 1	1.	0 1 1 1	L	1	DP L ←(AC)	The AC contents are transferred to the DPL.	_	
Data p	TLA	Transfer DPL to AC	1 1 1	<u> </u>	1001	1	1	AC -(DPL)	The DPL contents are transferred to the	ZF	
-	XAH	Exchange AC with DPH	0 0 1	<u> </u>	0011	1	1	(AC) ≒ (DPH)	The AC contents and the DPH contents are exchanged.		
putation instructions	XAT XAO XAI XA2 XA3	Exchange AC with working register At	1 1 1 1 1 1 1 1 1 1 1 1	000	0 0 0 0 0 1 0 0 1 0 0 1 1 0 0	1 1 1	1 1 1 1	(AC) = (A0) (AC) = (A1) (AC) = (A2) (AC) = (A3)	The AC contents and the contents of working register AO, A1, A2, or A3 specified by 1110 are exchanged.		
Norking register maniputation inst	XHa XHO XH1	Exchange DPH with working register Ha	1 1 1 1 1 1		a 1 0 0 0 1 1 0 0	1	1	(DPH) ≒(H0) (DPH) ≒(H1)	The DPH contents and the contents of working register H0 or H1 specified by a are exchanged.		
Workingre	XLa XLO XL1	Exchange DP _L with working register. La	1 1 1		0 0 0 1 0 0	;	1	(DPc)≒(LO) (DPc)≒(L1)	The DPL contents and the contents of working register LO or L1 specified by a are exchanged,		
2nc	SFB flag	Set flag bit	0 1 0	1	83 B2 B1 B0	1	7	Fn ← 1	A flag specified by B3B2B1B0 is set.		
Flag manipulation instructions	AFB flag	Reset flag bit	000	1	83 B2 B1 B0	1	1	Fn ←O	A flag specified by 83828180 is reset.	ZF	The flags are divided into 4 groups of F0 to F3. F4 to F7. F8 to F11. F12 to F1. F2 is set/reset according to the 4 bits including a single bit specified by immediate data 83828 180.
	JMP addr	Jump in the current bank	O 1 1 P ₇ P ₆ P ₅	- 1	1 P10P9P8 P3P2P1P0	2	2	PC ←PC11(Or PC11) P10P9 P8 P7 P6 P5 P4 P3 P2 P1 P0	A jump to an address specified by the PC11 for PC11) and immediate data P10 to P0 occurs.		If the BANK and JMP in structions are executed consecutively. PC11 →PC11.
ions	JPEA	Jump in the current page modified by E and AC	1 1 1	1	1010	1	1	PC7~0 ←(E.AC)	A jump to an address specified by the contents of the PC whose low-order B bits are replaced with the E and AC contents occurs.		
ine instructions	CZP addr	Call subroutine in the zero page	101	1	P3 P2 P1 P0	1	1	STACK ← (PC)+1 PC 11~6.PC 1~0 ←0 PC5~2←P3P2P1P0	A subroutine in page 0 of bank 0 is called.		
Jump/subroutine	CAL addr	Call subroutine in the zero bank	1 0 1 P7P5P5		1 PioPi Pio Pii Pio Pii Pio	2	2	STACK -(PC) +2 PC11-0 - OP10P9P8P7 P8P5P4P3P2P1P0	A subtoutine in bank 0 is called,		
٤	RT	Return from subroutine	0 1 1	0	0 0 1 0	1	1	PC ← (STACK)	A return from a subroutine occurs,		
	RTI	Return from interrupt	0 0 1	٥	0010	1	1	PC ←(STACK) CF ZF ← CSF. ZSF	A return from an interrupt servicing routine occurs.	ZF CF	
	BANK	Change bank	1 1 1	7	1 1 0 1	1	1	PC 11 - (PC11)	The bank is changed.	I I immed	ve only when used lately before the struction.
	BAt addr	Branch on AC bit	O 1 1 P7P6P5		0 0 tito P3 P2 P1 P0		2	PC7~0 - P7 P6P6 P4 P3 P2P1P0 11 ACL = 1	If a single bit of the AC specified by immediate data 110 is 1, a branch to an address specified by immediate data P7 to P0 within the current page occurs.		Mnemonic is BAO to BA3 according to the value of t,
	BNAt addr	Branch on no AC bit	O O 1 P7P6P5		0 0 tito P3P2P1P0	2	2	PC7~0 - P7 P6P5P4 P3P2P1P0 if AC1 = 0	If a single bit of the AC specified by immediate data 1100 is 0 e branch to an address specified by immediate data P7 to P0 within the current page occurs.		Mnemonic is BNA0 to BNA3 second- ing to the value of t.
	BMt addr	Branch on M bit			0 1 t i t o P3 P2 P1 P0		2	PC 7~0 ← P7 P6 P5 P4 P3 P2 P1 P0 If (M(DP. t 1 t 0)) = 1	If a single bit of the M(DP) specified by immediate data (110 is 1, a branch to an address specified by immediate data P7 to P0 within the current page occurs.		Mnemonic is BM0 to BM3 according to the value of t,
Branch instructions	BNMt addr	Branch on no M bit	O O 1 P1P5P5		0 1 t 1 t o P3 P2 P1 P0		2	PC7~0 ← P7 P6 P5 P4 P3 P2 P1 P0 if (M(DP, t 1 t 01) = 0	If a single bit of the M(DP) specified by immediate data £110 is 0, a branch to an address specified by immediate data P7 to P0 within the current page occurs.		Mnemonic is BNM0 to BNM3 accord- ing to the value of t.
Bran	BPt addr	Branch on Port bit			1 Otito P3P2P1P0		2	PC7~0 ← P7 P6 P5 P4 P3 P2 P1 P0 if (P(DPL tito)) = 1	If a single bit of port P(DPL) specified by immediate data t1(0 is 1, a branch to an address specified by immediate data P7 to P0 within the current page occurs.		Mnemonic is BP0 to BP3 according to the value of t.
	BNP1 addr	Branch on no Port bit	0 0 1 Pr P6 P5		1 Otito P3 P2 P1 P0		2	PC7~0 + P7P6P5P4 P3P2P1P0 If [P(DPL, t it 0)] = 0	If a single bit of port PIDPLI specified by immediate data tito is 0, a branch to an address specified by immediate data P7 to P0 within the current page occurs.		Mnemonic is BNPO to BNP3 according to the value of t.
	BTM addr	Branch on timer	0 1 1 P7P6P5	- 1	1 1 0 0 P3 P7 P1 P0	2	2	PC7~0 ← P7P6P5P4 P3P2P1P0 if TMF=1 then TMF ←0	If the TMF is 1, a branch to an address specified by immediate data P7 to P0 within the current page occurs. The TMF is reset.	TMF	

nstruction		Mnemonic	Instruct	ion code	20.0	Cycles	Function	Description	Status flag	Remarks
Inst			D7 D6 D5 D4	D ₃ D ₂ D ₁ D ₀	B,	ပ်			affected	
	BNTM addr	Branch on no timer	0 0 1 1 P7P6P5P4	1 1 0 0 P3 P2 P1 P0	2	2	PC7~0 ← P7 P6 P5 P4 P3 P2 P1 P0 if TMF = 0 then TMF ← 0	If the TMF is 0, a branch to an address specified by immediate date P7 to P0 within the current page occurs. The TMF is reset.	TMF	
	Bl addr	Branch on interrupt	O 1 1 F P7P6P5P4	1 1 0 1 P3P2P1P0	2	2	PC7~0 ← P1P6P5P4 P3P2P1P0 if EXTF = 1 then EXTF ← O	If the EXTF is 1, a branch to an address specified by immediate data P7 to P0 within the current page occurs. The EXTF is reset.	EXTF	
	BNI addr	Branch on no interrupt	0 0 1 1 P7 P6 P5 P4	1 1 0 1 P3 P2 P1 P0	2	2	PC 7~0 ← P7 P6 P6 P4 P3 P2 P1 P0 if EXTF = 0 then EXTF ← 0	If the EXTF is 0, a branch to an address specified by immediate data P7 to P0 within the current page occurs. The EXTF is reset.	EXTF	
tructions	BC addr	Branch on CF	0 1 1 1 P7P6P5P4	1 1 1 1 P3 P2 P1 Po	2	2	PC7~0 ← P7 P6 P5 P4 P3 P2 P1 P0 If CF = 1	If the CF is 1, a branch to an address specified by immediate data P7 to P0 within the current page occurs.		
Branch instructions	BNC addr	Branch on no CF	0 0 1 1 P7P6P5P4	1 1 1 1 P3P2P1P0	2	2	PC 7 ~0 ← P7 P6 P5 P4 P3 P2 P1 P0 if CF =0	If the CF is 0, a branch to an address specified by immediate data P7 to Pg within the current page occurs.		
	82 addr	Branch on ZF	0 † 1 1 P7P6P5P4	1 1 1 0 P3 P2 P1 P0	2	2	PC7~0~P7P6P5P4 P3P2P1P0 11 ZF=1	If the ZF is 1, a branch to an address specified by immediate data P7 to P0 within the current page occurs.		
	BNZ addr	Branch on no ZF	0 0 1 1 P7P6P5P4	1 1 1 0 P3 P2 P1 P0	2	2	PC7~0 ← P7 P6 P5 P4 P3 P2 P1 P0 If ZF = 0	If the ZF is 0, a branch to an address specified by immediate data P7 to P0 within the current page occurs.		
	BFn addr	Branch on flag bit	1 1 0 1 P7P6P5P4	n3 n2 n1 n0 P3 P2 P1 P0	2	2	PC7~0 ←P7P6P5P4 P3P2P1P0 if Fn = 1	If a flag bit of the 16 flags specified by immediate data n3n2n1n0 is 1, a branch to an address specified by immediate data P7 to P0 within the current page occurs.		Mnemonic is BF0 to BF15 according to the value of n.
	BNFn addr	Branch on no flag bit	1 0 0 1 P7P6P5P4	n 3 n 2 n 1 n 0 P 3 P 2 P 1 P 0	2	2	PC 7 ~ 0 ← P7 P6 P6 P4 P3 P2 P1 P0 if Fn = 0	If a flag bit of the 16 flags specified by immediate data ngngn1n0 is 0, a branch to an address specified by immediate data P7 to P0 within the current page occurs.		Mnemonic is SNF0 to BNF 15 according to the value of n.
۶۰.	1P	Input port to AC	0000	1 1 0 0	1	1	AC (P(DPLI)	The contents of port P(DPL) are inputted to the AC.	ZF	
oction	OP	Output AC to port	0 1 1 0	0001	1	1	P(DPL) ←(AC)	The AC contents are outputted to port P(DPL).		
Input/output instructions	SPB bit	Set port bij	0000	O 1 B1 B0	1	2	P(DP1 B180) -1	Immediate data 8180-specified one bit in port P(DPL) is set.		Mnemonic is BNF0 to BNF 15 according to the value of n.
Input/o	RPB bit	Reset port bit	0010	0 1 8180	1	2	P(DP1. B1B0) ←0	Immediate data 8180-specified one bit in port P (DPL) is reset.	ZF	When this in- struction is executed, the E register contents are
	SCTL bit	Set control register bit(S)	0010	1 1 0 0 B3 B2 B1 B0	2	2	CTL ←(CTL) V B3 B2 B1 B0	Immediate data B3B2B1B0-specified bits in the control register are set.		destrayed.
instructions	RCTL bit	Reset control register bit(S)	0 0 1 0 1 0 0	1 1 0 0 B3 B2 B1 B0	2	2	CTL ←(CTL) A B3 B2 B1 B0	Immediate data B3B2B1B0-specified bits in the control register are reset.	ZF	
Other instr	WTTM	Write Limer	1 1 1 1	1 0 0 1	1	1	TM+(E).(AC) TMF +0	The E and AC contents are loaded in the timer. The TMF is reset.	TMF	
0	HALT	Hal 1	1 1 1 1	0110	1	1	Hal1	The standby mode is entered.		
	NOP	No operation	0000	0000	1	1	No operation	No operation is performed, but 1 machine cycle is consumed.		

- *1 If the LI instruction or CLA instruction is used consecutively in such a manner as LI, LI, LI,, or CLA, CLA, CLA,, the first LI instruction or CLA instruction only is effective and the following LI instructions or CLA instructions are changed to the NOP instructions.
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